

In the Claims:

Please cancel claims 1-8 without prejudice or disclaimer of the subject matter thereof.

Please add the following claims:

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18. (Newly Added) A semiconductor device, comprising:
a semiconductor element having a circuit forming surface;
a wiring disposed on said circuit forming surface and on a side surface of said semiconductor element;
a sealed bump electrode connected to said wiring, said sealed bump electrode having an exposed surface;
a ball electrode disposed on said exposed surface of said bump electrode; and
a sealed confronting surface of said circuit forming surface.
19. (Newly Added) A semiconductor device as recited in claim 18, further comprising a plurality of electrodes on said circuit forming surface.
20. (Newly Added) A semiconductor device as recited in claim 18, wherein said wiring on said side surface has an end that is sealed.
21. (Newly Added) A semiconductor device as recited in claim 18, wherein said sealed bump electrode and said sealed confronting surface are resin sealed.
22. (Newly Added) A semiconductor device as recited in claim 18, wherein said sealed confronting surface is entirely sealed.
23. (Newly Added) A semiconductor device as recited in claim 18, wherein the semiconductor device is mounted on another semiconductor device with said confronting surface as a contacting surface.